IN THE CLAIMS

No amendments have been made to the claims.

Claims 1-5 (cancelled)

6. (previously presented) A method of forming copper interconnect, comprising:

forming a barrier layer over a substrate having at least one trench therein;

forming a copper seed layer on the surface of the barrier layer;

forming a copper layer over the barrier and seed layers;

removing a portion of the copper layer by chemical mechanical polishing with a first slurry comprising a chelating organic acid buffer system, colloidal silica, and a low electrochemical oxidizer; and

removing at least a portion of the barrier layer by chemical mechanical polishing with a second slurry comprising a chelating organic acid buffer system, and colloidal silica;

wherein the second slurry is formed without the oxidizer.

7. (original) The method of Claim 6, wherein the barrier layer comprises tantalum.

8. (original) The method of Claim 7, wherein the chelating organic acid buffer system comprises citric acid and potassium citrate.

9. (original) The method of Claim 8, wherein the oxidizer comprises hydrogen peroxide.

10. (original) The method of Claim 9, wherein the first slurry further comprises a corrosion inhibitor.

11. (original) The method of Claim 10, wherein the first slurry has a pH in the range of 3 to 6, and the corrosion inhibitor comprises benzotriazole.

12. (withdrawn) A slurry produced by the process comprising:

combining citric acid, potassium citrate, silica, hydrogen peroxide, and benzotriazole.

13. (withdrawn) The slurry produced by the process of Claim 12, wherein a concentration of citric acid is approximately 3g/l, a concentration of potassium citrate is approximately 3g/l, a concentration of silica is approximately 5 wt. %, a concentration of hydrogen peroxide is approximately 3 wt. %, and a concentration of benzotriazole is approximately 0.015 molar.

14. (withdrawn) The slurry produced by the process of Claim 13, further comprising combining the citric acid, potassium citrate, silica, hydrogen peroxide, and benzotriazole with water.

15. (withdrawn) A slurry, comprising:

approximately 3 grams/liter of citric acid;

approximately 3 grams/liter of potassium citrate;

approximately 5 wt.% silica;

approximately 3 wt.% hydrogen peroxide;

approximately 0.015 molar benzotriazole; and

the mixture and reaction products thereof.

16. (withdrawn) The slurry of Claim 15, wherein the slurry has a pH in the range of 3 to 6.

17. (withdrawn) A slurry formed by the process of combining a organic acid, an organic acid salt; approximately 5 wt.% silica; approximately 3 wt.% hydrogen peroxide; and approximately 0.015 molar benzotriazole.

18. (withdrawn) The slurry of Claim 17, wherein the organic acid comprises acetic acid.

19. (withdrawn) The slurry of Claim 18, wherein the organic acid salt comprises potassium acetate.

20. (withdrawn) The slurry of Claim 17, wherein the organic acid comprises 3 grams/liter of citric acid, and the organic acid salt comprises 3 grams/liter of potassium citrate.

21. (withdrawn) A slurry for polishing copper diffusion barriers, comprising:

approximately 3 grams/liter of citric acid;

approximately 3 grams/liter of potassium citrate;

approximately 5 wt.% silica;

approximately 0.015 molar benzotriazole; and

the mixture and reaction products thereof.

22. (withdrawn) The slurry of Claim 21, wherein the copper diffusion barriers comprise tantalum.

23. (withdrawn) The slurry of Claim 21, wherein the slurry has a pH in the range of 3 to 6.

24. (withdrawn) A slurry for polishing barriers comprised of tantalum, comprising:

organic acid, an organic acid salt, an abrasive, a corrosion inhibitor, and the mixture and reaction products thereof, and wherein no oxidizer is included.

25. (withdrawn) The slurry of Claim 24, wherein the organic acid comprise citric acid.

26. (withdrawn) The slurry of Claim 24, wherein the corrosion inhibitor comprises benzotriazole, and wherein the slurry has a pH in the range of 3 to 6.

27. (withdrawn) The slurry of Claim 25, wherein the organic acid salt comprises potassium citrate.